



US00D805486S

(12) **United States Design Patent** (10) **Patent No.:** **US D805,486 S**
Hochman et al. (45) **Date of Patent:** **** Dec. 19, 2017**

(54) **ELECTRONICS ENCLOSURE**

(71) Applicant: **Revolution Display, LLC**, Glendale,
CA (US)

(72) Inventors: **Jeremy Hochman**, Walnut, CA (US);
Andrew U. Pae, Simi Valley, CA (US);
Scott M. Blair, Austin, TX (US)

(73) Assignee: **Revolution Display, LLC**, Glendale,
CA (US)

(**) Term: **15 Years**

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(51) **LOC (10) Cl.** **13-99**

(52) **U.S. Cl.**

USPC **D13/184**; D13/110; D14/356; D14/300

(58) **Field of Classification Search**

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D14/388, 432, 496, 125, 140, 142, 155,
D14/168, 240, 243, 299, 188, 300, 301;
D13/103, 107, 108, 123, 152, 158, 159,
D13/162.1, 182, 199, 110, 151, 162, 184,
D13/179, 180

CPC H05B 37/00; H05B 41/00; H05B 39/00;
H05B 39/02; H05B 39/04; H05B 39/041;
H05B 39/045; H05B 39/08; G06F 1/00;
G06F 1/02; G06F 1/1635; G06F 1/18;
G06F 1/181; G06F 1/189; G06F 1/206;
G06F 21/00; H05K 5/00

See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

D267,949 S * 2/1983 Hisatsune D14/188
D281,315 S * 11/1985 Kjeld D13/179
D335,670 S * 5/1993 Kerr D13/184
D368,261 S * 3/1996 Shushurin D13/110
D377,335 S * 1/1997 Katooka D13/110

D386,148 S * 11/1997 Katooka D13/110
D400,167 S * 10/1998 Klaus D13/110
D402,627 S * 12/1998 Klaus D13/110
D421,598 S 3/2000 Berusha et al.
D429,225 S * 8/2000 Halliday D13/184
D431,816 S * 10/2000 Beaumont D14/188

(Continued)

FOREIGN PATENT DOCUMENTS

CA 81279 7/1997

OTHER PUBLICATIONS

Aitech, Embedded Computing Without Compromise, Dual VME
Slot Enclosure (Jun. 29, 2017).

(Continued)

Primary Examiner — Susan Bennett Hattan

Assistant Examiner — Marie D. Fast Horse

(74) *Attorney, Agent, or Firm* — Downs Rachlin Martin
PLLC

(57)

CLAIM

The ornamental design for an electronics enclosure, as
shown and described.

DESCRIPTION

FIG. 1 is a perspective view of an electronics enclosure
showing our new design;

FIG. 2 is an end view thereof;

FIG. 3 is a second end view thereof;

FIG. 4 is a side view thereof;

FIG. 5 is a second side view thereof;

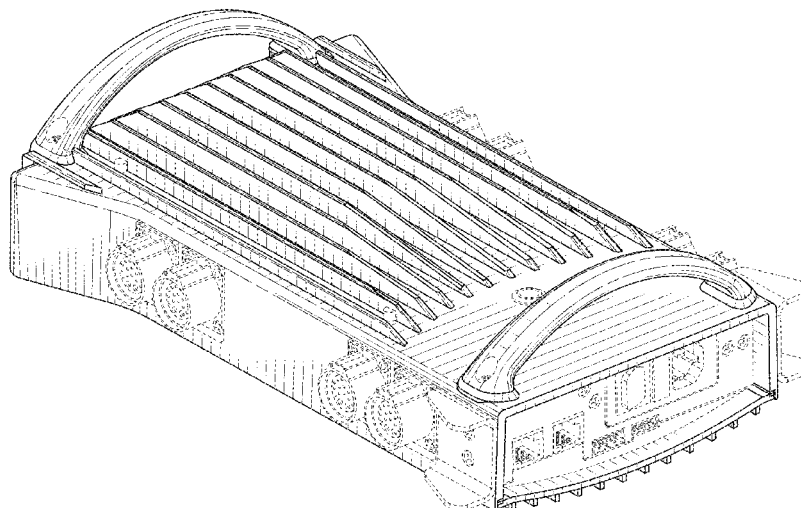
FIG. 6 is a top view thereof; and,

FIG. 7 is a bottom view thereof.

The broken lines in the Figures are for the purpose of
illustrating unclaimed portions of the electronics enclosure
and form no part of the claimed design.

The shade lines in the Figures show contour and not surface
ornamentation.

1 Claim, 5 Drawing Sheets



(56)

References Cited

U.S. PATENT DOCUMENTS

D436,918	S	*	1/2001	Matsuda		D13/110
D437,288	S	*	2/2001	Light		D13/110
D464,327	S	*	10/2002	Frank, Jr.		D13/162
D469,401	S	*	1/2003	Griffey		D13/110
D474,738	S	*	5/2003	Ishii		D13/110
D479,195	S	*	9/2003	Krieger		D13/110
D486,446	S	*	2/2004	Hriscu		D13/110
D489,682	S	*	5/2004	Guillarme		D13/110
D499,074	S	*	11/2004	Cook et al.		D13/110
D503,676	S	*	4/2005	Krieger		D13/110
D505,915	S	*	6/2005	Hussaini		D13/110
D507,528	S	*	7/2005	Feldman		D13/102
D510,736	S	*	10/2005	Chen		D14/300
D513,247	S	*	12/2005	Matsuoka		D14/188
D516,554	S	*	3/2006	Richardson et al.		D14/188
D520,985	S	*	5/2006	Ishinabe		D14/188
D538,260	S	*	3/2007	Wada		D13/110
D538,742	S	*	3/2007	Pickvet		D13/110
D540,253	S	*	4/2007	Tsai		D13/110
D546,282	S	*	7/2007	Wardenburg		D13/110
D548,695	S	*	8/2007	Krieger		D14/188
D549,214	S	*	8/2007	Uehara		D13/110
D551,621	S	*	9/2007	Iacovelli		D13/110
D561,688	S	*	2/2008	Hussaini		D13/110
D565,030	S	*	3/2008	Amit		D14/432
D577,668	S	*	9/2008	Buck		D14/300
D585,439	S	*	1/2009	Ching		D14/432
D586,814	S	*	2/2009	Kramer		D13/110
D595,647	S	*	7/2009	Shum		D14/432
D600,698	S	*	9/2009	Kramer		D13/110
D610,539	S	*	2/2010	Dahan		D13/162
D616,376	S	*	5/2010	Lannoch		D14/301
D617,788	S	*	6/2010	Crisp		D13/162
D619,104	S	*	7/2010	Boyland		D13/101
D620,432	S	*	7/2010	Chen		D13/110
D621,350	S	*	8/2010	Huang		D13/110
D621,351	S	*	8/2010	Huang		D13/110
D649,141	S	*	11/2011	Thomas et al.		D13/184
D655,280	S	*	3/2012	MacManus et al.		D14/188
D684,130	S	*	6/2013	Vincent		D13/110
D690,738	S	*	10/2013	York		D13/110
D697,901	S	*	1/2014	Gae et al.		D13/110
D709,449	S	*	7/2014	Oba		D13/110
D713,336	S	*	9/2014	Penn		D13/110
D716,730	S	*	11/2014	Liu		D14/496
D721,738	S	*	1/2015	Hochman		D14/365
D730,333	S	*	5/2015	Matsumoto		D13/110
D737,817	S	*	9/2015	Starck		D13/180
D739,347	S	*	9/2015	Huang		D13/110
D751,998	S	*	3/2016	Hochman		D13/110
D780,692	S	*	3/2017	Hopponen		D13/184
D786,204	S	*	5/2017	Hochman		D26/76
D786,475	S	*	5/2017	Hargreaves		D14/357
D789,931	S	*	6/2017	Drew		H05B 41/00
2006/0214592	A1	*	9/2006	Hopkins		315/56
2011/0111636	A1	*	5/2011	Zheng		H01R 31/06
						439/650

OTHER PUBLICATIONS

Aitech, Embedded Computing Without Compromise, Full ATR Short VME Enclosure (Jun. 29, 2017).

* cited by examiner

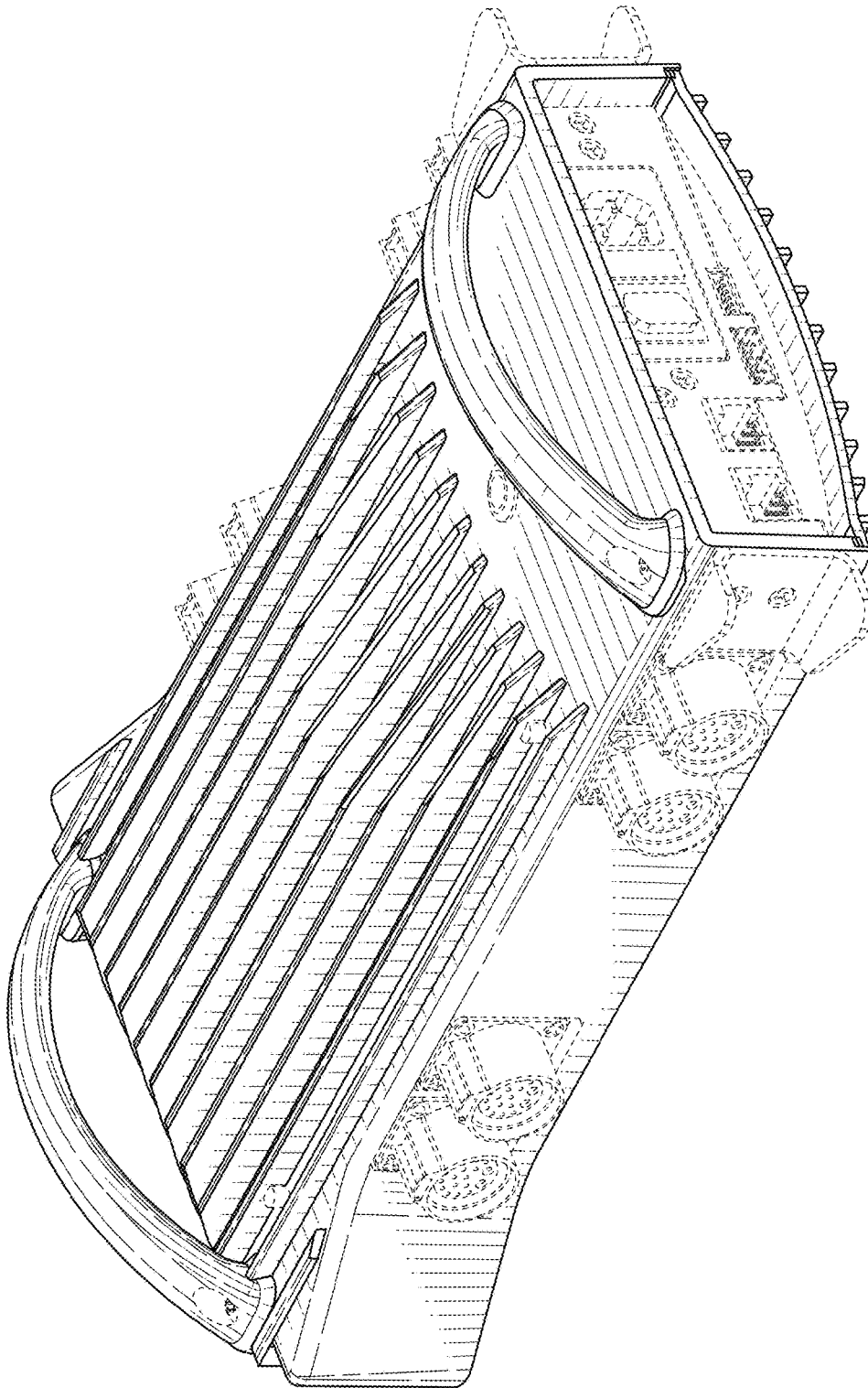


FIG. 1

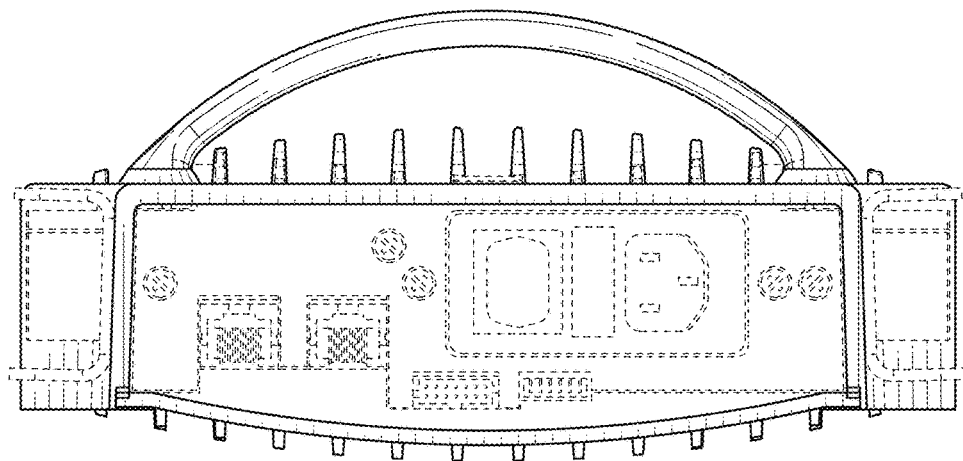


FIG. 2

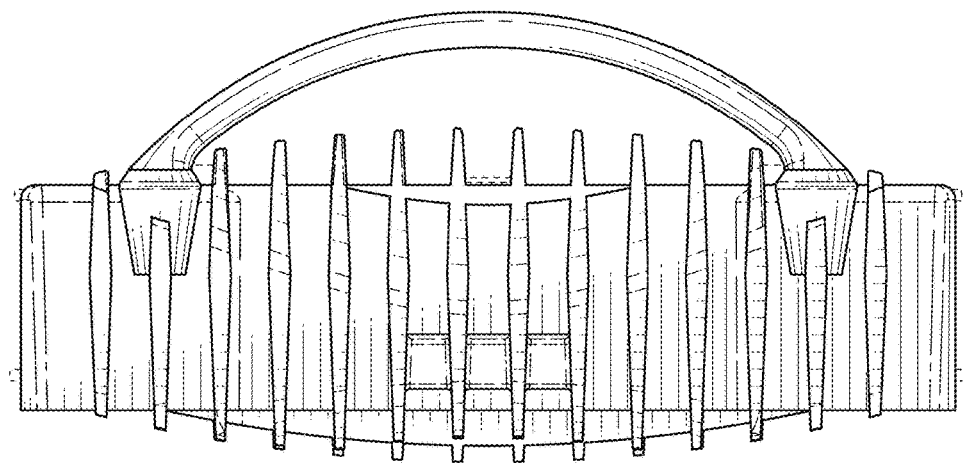


FIG. 3

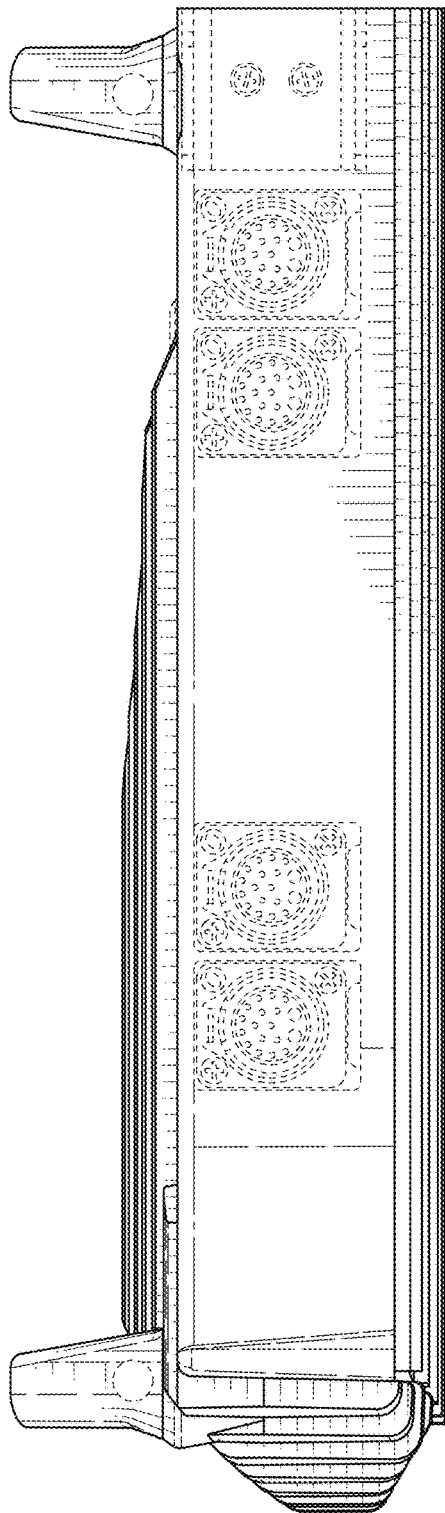


FIG. 4

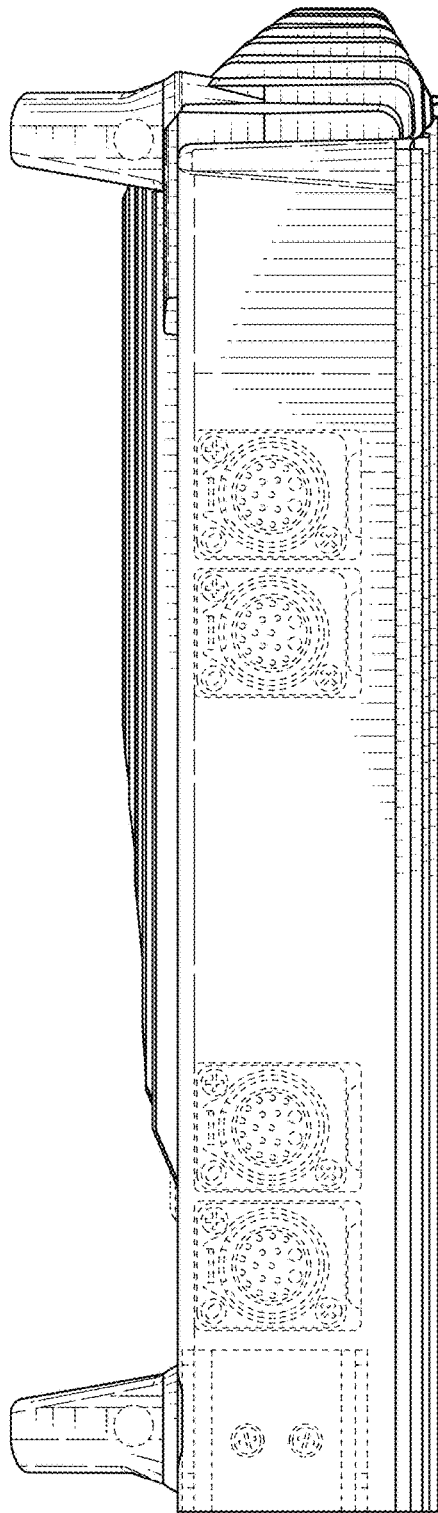


FIG. 5

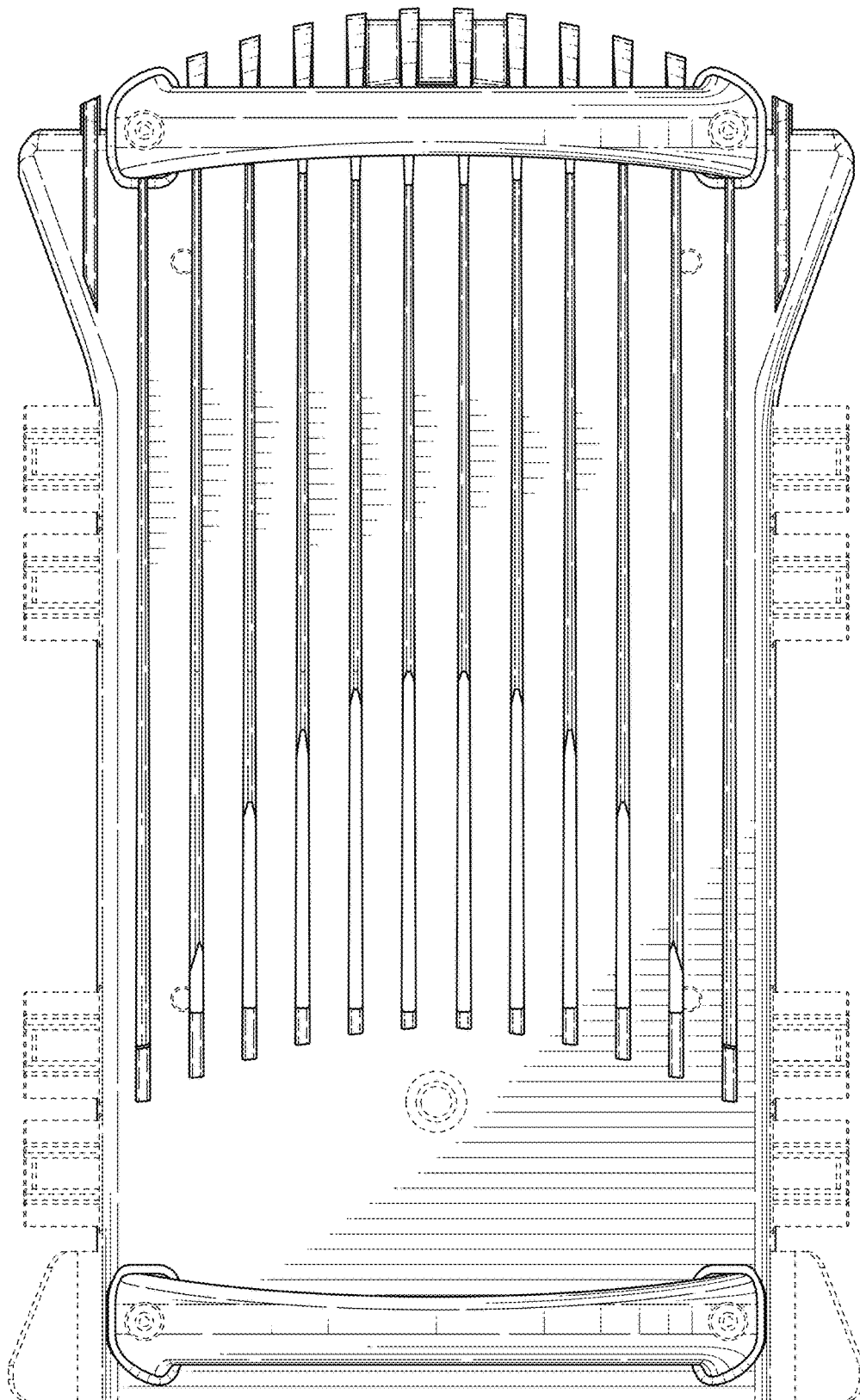


FIG. 6

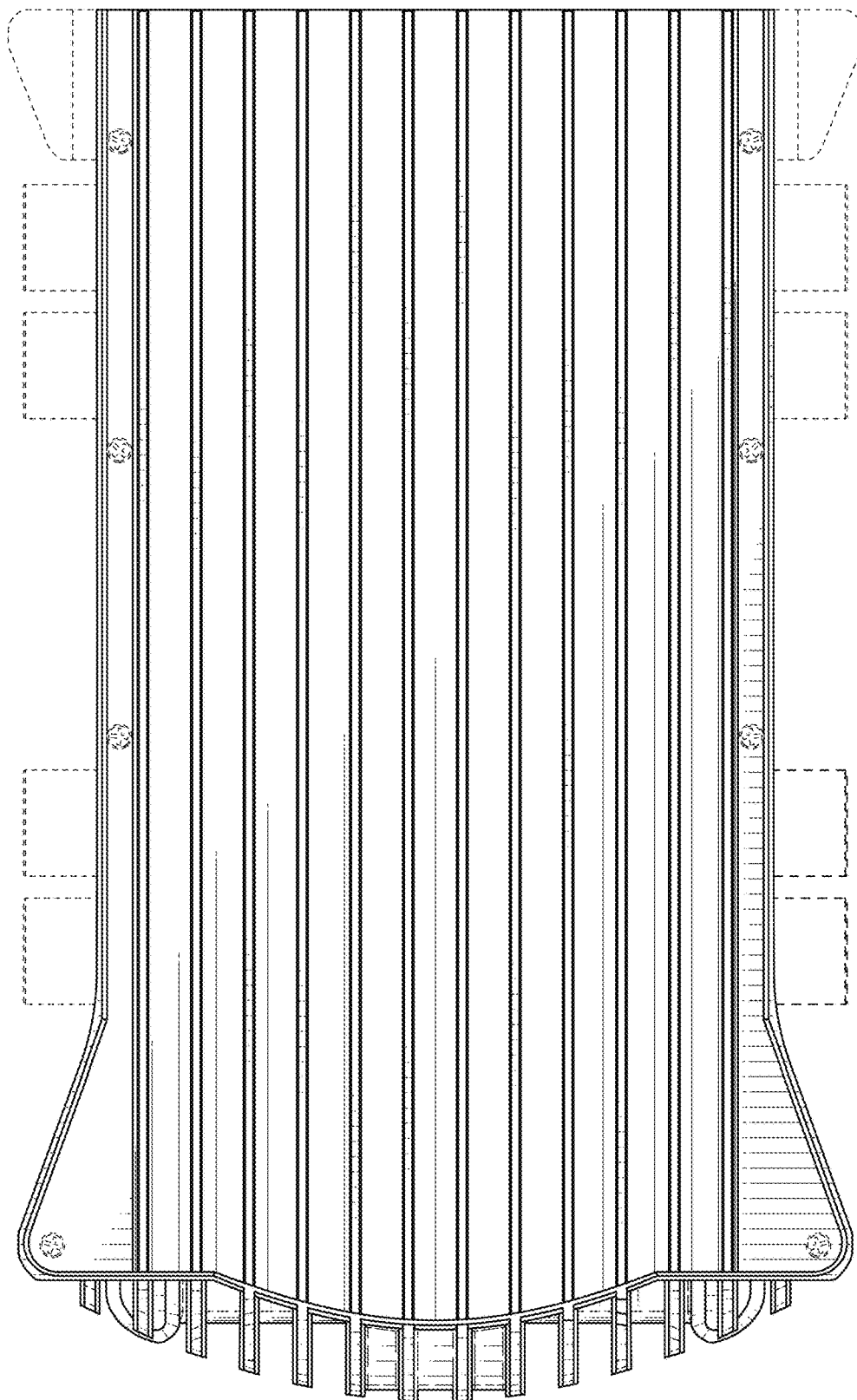


FIG. 7